Chip Monolithic Ceramic Capacitors



High Frequency for Flow/Reflow Soldering

■ Features

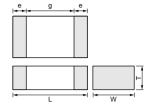
- 1. HiQ and low ESR at VHF, UHF, Microwave.
- Feature improvement, low power consumption for mobile telecommunication. (Base station, terminal, etc.)

■ Applications

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High-frequency circuit (Mobile telecommunication, etc.)





Part Number	Dimensions (mm)						
Part Number	L	W	T	е	g min.		
GQM188	1.6 ±0.1	0.8 ±0.1	0.8 ±0.1	0.2 to 0.5	0.5		
GQM219	2.0 ±0.1	1.25 ±0.1	0.85 ±0.1	0.2 to 0.7	0.7		

Part Number	GQI	QM18 GQM21		M21	
LxW	1.60x0.80		2.00x1.25		
тс	CC (5	COG (5C)		OG C)	
Rated Volt.	100 (2A)	50 (1H)	100 (2A)	50 (1H)	
Capacitance (Capacit	tance part numbering code)	and T (mm) Dimension (T Dimen	sion part numbering code)		
0.50pF(R50)	0.80(8)		0.85(9)		
0.75pF(R75)	0.80(8)		0.85(9)		
1.0pF(1R0)	0.80(8)		0.85(9)		
1.1pF(1R1)	0.80(8)		0.85(9)		
1.2pF(1R2)	0.80(8)		0.85(9)		
1.3pF(1R3)	0.80(8)		0.85(9)		
1.5pF(1R5)	0.80(8)		0.85(9)		
1.6pF(1R6)	0.80(8)		0.85(9)		
1.8pF(1R8)	0.80(8)		0.85(9)		
2.0pF(2R0)	0.80(8)		0.85(9)		
2.2pF(2R2)	0.80(8)		0.85(9)		
2.4pF(2R4)	0.80(8)		0.85(9)		
2.7pF(2R7)	0.80(8)		0.85(9)		
3.0pF(3R0)	0.80(8)		0.85(9)		
3.3pF(3R3)	0.80(8)		0.85(9)		
3.6pF(3R6)	0.80(8)		0.85(9)		
3.9pF(3R9)	0.80(8)		0.85(9)		
4.0pF(4R0)	0.80(8)		0.85(9)		
4.3pF(4R3)	0.80(8)		0.85(9)		
4.7pF(4R7)	0.80(8)		0.85(9)		
5.0pF(5R0)	0.80(8)		0.85(9)		
5.1pF(5R1)	0.80(8)		0.85(9)		
5.6pF(5R6)	0.80(8)		0.85(9)		
6.0pF(6R0)	0.80(8)		0.85(9)		
6.2pF(6R2)	0.80(8)		0.85(9)		
6.8pF(6R8)	0.80(8)		0.85(9)		
7.0pF(7R0)		0.80(8)	0.85(9)		
7.5pF(7R5)		0.80(8)	0.85(9)		
8.0pF(8R0)		0.80(8)	0.85(9)		
8.2pF(8R2)		0.80(8)	0.85(9)		
9.0pF(9R0)		0.80(8)	0.85(9)		
9.1pF(9R1)		0.80(8)	0.85(9)		
10pF(100)		0.80(8)	0.85(9)		

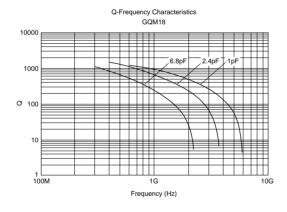
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Part Number	GQN	M18	GQM21		
LxW	1.60x	0.80	2.00x1.25		
тс	C0G (5C)		C0G (5C)		
Rated Volt.	100 (2A)	50 (1H)	100 (2A)	50 (1H)	
Capacitance (Ca	pacitance part numbering code)	and T (mm) Dimension (T Dimen	sion part numbering code)		
11pF(110)		0.80(8)	0.85(9)		
12pF(120)		0.80(8)	0.85(9)		
13pF(130)		0.80(8)	0.85(9)		
15pF(150)		0.80 (8)	0.85(9)		
16pF(160)		0.80(8)	0.85(9)		
18pF(180)		0.80 (8)	0.85(9)		
20pF(200)		0.80(8)		0.85(9)	
22pF(220)		0.80(8)		0.85(9)	
24pF(240)		0.80(8)		0.85(9)	
27pF(270)				0.85(9)	
30pF(300)				0.85(9)	
33pF(330)				0.85(9)	
36pF(360)				0.85(9)	
39pF(390)				0.85(9)	
43pF(430)				0.85(9)	
47pF(470)				0.85 (9)	

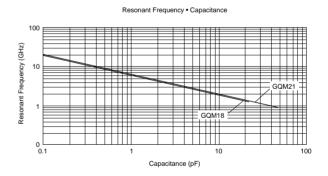
The part numbering code is shown in ().

Dimensions are shown in mm and Rated Voltage in Vdc.

■ Q-Frequency Characteristics



■ Resonant Frequency-Capacitance



Specifications and Test Methods

No.	lo. Item S		Specifications		Test Me	thod		
1	Operating Temperatu	ıre	5C : −55°C to 125°C					
2	2 Rated Voltage		See the previous page.	The rated voltage is defined as the maximum voltage which may be applied continuously to the capacitor. When AC voltage is superimposed on DC voltage, V ^{p-p} or V whichever is larger, should be maintained within the rated voltage range.		ge, VP-P or VO-P,		
3	Appearar	nce	No defects or abnormalities	Visual inspection				
4	Dimensio	n	Within the specified dimensions	Using calipers				
5	Dielectric	: Strength	No defects or abnormalities	No failure should be observed when 300% of the rated voltage is applied between the terminations for 1 to 5 seconds, provided the charge/discharge current is less than 50mA.			conds,	
6	Insulation	Resistance	More than 10,000M Ω or 500 Ω • F (whichever is smaller)	voltage not exceeding	ne insulation resistance should be measured with a DC oltage not exceeding the rated voltage at 25°C and 75%RH ax. and within 2 minutes of charging.			
7	Capacita	nce	Within the specified tolerance	The capacitance/Q s			at the	
8	Q	30pF min. : Q≥1000 30pF max. : Q≥400+20C		Item Cha		(1000pF and t 1±0.1MHz	pelow)	
			C : NominalCapacitance (pF)	Voltage		0.5 to 5Vrms	3	
	Capactance Change Temperature Coefficent		Within the specified tolerance (Table A)	The temperature coefficient is determind using the capacital measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through the capacitance should be within the specified tolerance for the temperature coefficient and capacitance change as in Table 2.			•	
			Within the specified tolerance (Table A)				lerance for the	
9	Capacitance Temperature Characteristics Capacitance Drift	Capacitance Drift	Within ±0.2% or ±0.05pF (Whichever is larger.)	The capacitance drift is caluculated by dividing the different between the maximum and minimum measured values in steps 1, 3 and 5 by the capacitance. value in step 3. Step Temperature (°C) 1 25±2 2 -55±3 3 25±2 4 125±3 5 25±2			values in the ep 3.	
40	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.		Solder the capacitor to the test jig (glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N* force in parallel with the test jig for 10±1sec. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. *5N (GQM188)			
10				Type	а	b	С	
				GQM18	1.0	3.0	1.2	
			Solder resist	GQM21 GQM32	1.2 2.2	4.0	1.65 2.9	
			Baked electrode or copper foil	GQM32	Fig .	5.0	(in mm)	
	Appearance No defects or abnormalities Capacitance Within the specified tolerance Vibration Resistance Q 30pF min. : Q≥1000 30pF max. : Q≥400+20C		No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board) in the				
11			30pF min. : Q≥1000	same manner and under the same conditions as (10). The capacitor should be subjected to a simple harmonic m having a total amplitude of 1.5mm, the frequency being va uniformly between the approximate limits of 10 and 55Hz. frequency range, from 10 to 55Hz and return to 10Hz, show be traversed in approximately 1 minute.			armonic motion y being varied and 55Hz. The 10Hz, should	
			от топинатоврания (рг.)	This motion should be applied for a period of 2 hours in ea 3 mutually perpendicular directions (total of 6 hours).				

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Specifications and Test Methods

Continued from the preceding page Specifications No Item Test Method Solder the capacitor on the test jig (glass epoxy board) shown No crack or marked defect should occur in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 50 Pressunzing speed: 1.0mm/sec. Pressunze Deflection 100 t: 1.6mm b С Type а Flexure : ≤1 GQM18 1.0 3.0 1.2 GOM21 1.65 12 40 Capacitance meter GQM32 2.2 5.0 2.9 45 (in mm) Fig. 2 Fig. 3 Immerse the capacitor in a solution of ethanol (JIS-K-8101) and Solderability of 75% of the terminations are to be soldered evenly rosin (JIS-K-5902) (25% rosin in weight propotion). Preheat at Termination 80 to 120°C for 10 to 30 seconds. After preheating, immerse in and continuously. eutectic solder solution for 2±0.5 seconds at 230±5°C. The measured and observed characteristics should satisfy the specifications in the following table. Appearance No marking defects Within $\pm 2.5\%$ or ± 0.25 pF Canacitance Change (Whichever is larger) Preheat the capacitor at 120 to 150℃ for 1 minute. Immerse the Resistance 30pF min. : Q≥1000 to Soldering capacitor in a eutectic solder solution at 270±5℃ for 10±0.5 14 30pF max. : Q≥400+20C Heat seconds. Let sit at room temperature for 24±2 hours. 0 C: NominalCapacitance (pF) More than $10,000M\Omega$ or $500\Omega \bullet F$ (Whichever is smaller) I.R. Dielectric No failure Strength The measured and observed characteristics should satisfy the specifications in the following table. Fix the capacitor to the supporting jig in the same manner and Appearance No marking defects under the same conditions as (10). Within $\pm 2.5\%$ or ± 0.25 pF Capacitance Perform the five cycles according to the four heat treatments (Whichever is larger) Change listed in the following table. Temperature Let sit for 24±2 hours at room temperature, then measure. 30pF min. : Q≥1000 Cycle 30pF max. : Q≥400+20C Step Q Min. Operating Room Max. operating Room Temp. (℃) C: NominalCapacitance (pF) Temp.+0/-3 Temp.+3/-0 Temp. Temp. Time (min.) 30±3 30±3 2 to 3 2 to 3 More than $10,000M\Omega$ or $500\Omega \bullet F$ (Whichever is smaller) I.R. Dielectric No failure Strength The measured and observed characteristics should satisfy the specifications in the following table. Appearance No marking defects Capacitance Within $\pm 5\%$ or ± 0.5 pF Change (Whichever is larger) Let the capacitor sit at 40±2℃ and 90 to 95% humiduty for Humidity 30pF min. : Q≥350 500±12 hours. 16 Steady 10pF and over, 30pF and below : Q≥275+5C/2 Remove and let sit for 24±2 hours (temperature compensating State Q 10pF max. : Q≥200+10C type) at room temperature, then measure. C: Nominal Capacitance (pF) More than 1,000M $\!\Omega$ or 50Ω • F (Whichever is smaller) I.R. Dielectric No failure Strength

Note Please read rating and \(\triangle CAUTION \) (for storage, operating, rating, soldering, mounting and handling) in this PDF catalog to prevent smoking and/or burning, etc. This catalog has only typical specifications. Therefore, you are requested to approve our product specifications or to transact the approval sheet for product specifications before ordering

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Specifications and Test Methods

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No.	Item Specifications		Specifications	Test Method		
17			The measured and observed characteristics should satisfy the specifications in the following table.			
		Appearance	No marking defects			
		Capacitance Change	Within ±7.5% or ±0.75pF (Whichever is larger)	Apply the rated voltage at 40±2℃ and 90 to 95% humidity for		
	Humidity Load	Q	30pF min. : Q≥200 30pF max. : Q≥100+10C/3	500±12 hours. Remove and let sit for 24±2 hours at room te prature then muasure. The charge/discharge current is less than 50mA.		
			C : Nominal Capacitance (pF)			
		I.R.	More than 500MΩ or 25Ω • F (Whichever is smaller)			
		Dielectric Strength	No failure			
			The measured and observed characteristics should satisfy the specifications in the following table.			
		Appearance	No marking defects			
		Capacitance Change	Within ±3% or ±0.3pF (Whichever is larger)	Apply 200% of the rated voltage for 1000±12 hours at the		
18	High Temperature Load	Q	30pF min. : Q≥350 10pF and over, 30pF and below : Q≥275+5C/2 10pF max. : Q≥200+10C	maximun operating temperature ±3°C. Let sit for 24±2 hours (temperature compensating type) at room temperature, then measure. The charge/discharge current is less than 50mA.		
			C : Nominal Capacitance (pF)	_		
		I.R.	More than 1,000MΩ or 50Ω • F (Whichever is smaller)			
		Dielectric Strength	No failure			

Table A

	Ni a sa tra a li Mala sa a	Capacitance Change from 25℃ (%)						
Char.	Nominal Values (ppm/°C) Note 1	-55		-30		-10		
		Max.	Min.	Max.	Min.	Max.	Min.	
5C	0±30	0.58	-0.24	0.40	-0.17	0.25	-0.11	

Note1 : Nominal values denote the temperature coefficient within a range of 25℃ to 125℃ (for 5C)

